

Recommended Reflow Soldering Conditions

This package is Surface Mount Device (SMD).

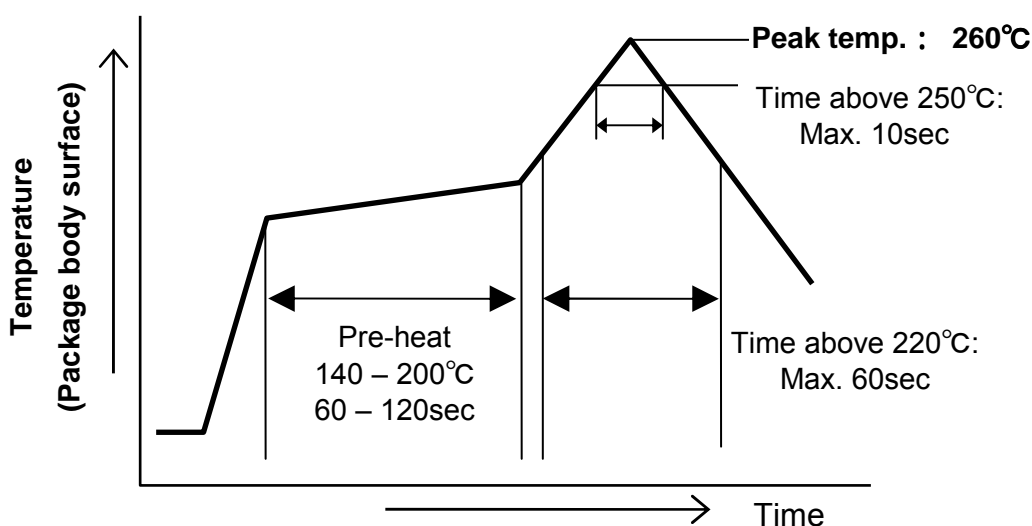
The resistance to soldering heat with SMD depends on storage conditions, soldering methods, and soldering conditions.

Please assemble packages according to the following conditions.

Recommended Storage Conditions

	Conditions	Time
Before opening dry pack:	≤30°C85%RH	1 year
After opening dry pack:	≤30°C70%RH	1 month (720 hours)

Recommended Reflow Profile



This package should be assembled with IR reflow, Full convection, or IR/Convection.

The allowable number of times with the reflow is Max. 2 times. This must be done in the above-mentioned condition (after opening dry pack).

* Soldering iron conditions (for packages with leads)

Temperature (Tip of the iron): ≤350°C, Time: ≤5sec, Max. 2 times / lead

Recommended Bake Conditions

When packages exceed the above-mentioned storage conditions after opening the dry pack, please bake them according to the following conditions:

Temperature	Time	Number of times
125±5°C	20 - 36 hours	Max. 2 times

Storage conditions from the baking to the reflow soldering are the same as the above-mentioned storage conditions.

* If products are shipped in Tape & Reel, please transfer them to heatproof trays before baking.